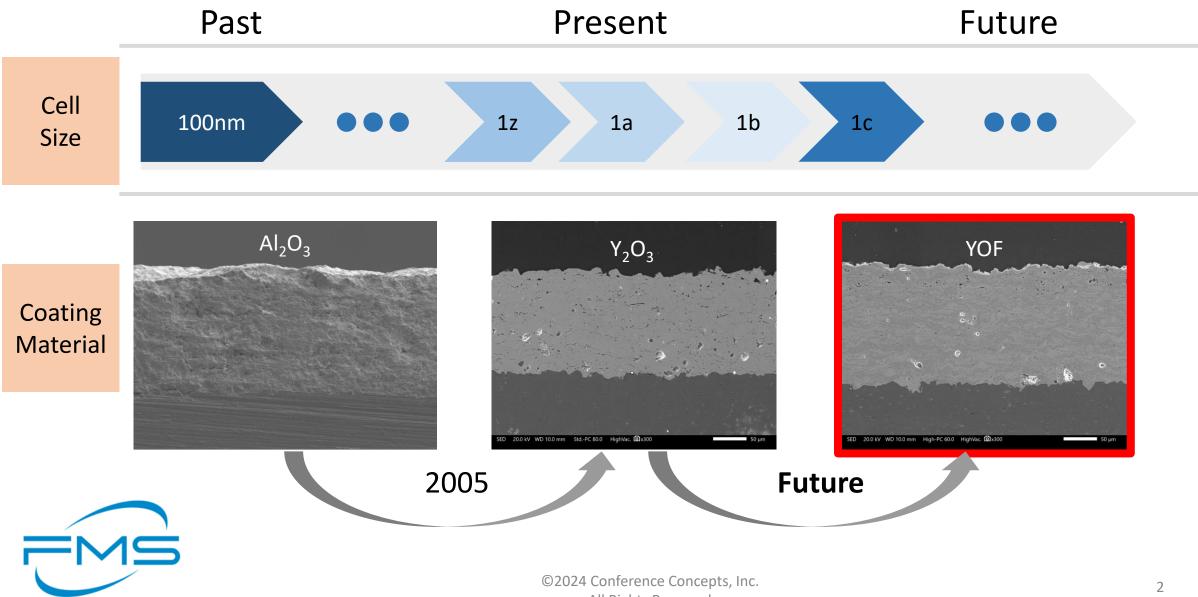
# Plasma Etching Behavior of Y<sub>2</sub>O<sub>3</sub> coatings

# by SF<sub>6</sub> Plasma Pre-Treatment

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# DRAM scaling down challenges & overcome



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### Background: Problem after replacing the inner chamber wall

- Y<sub>2</sub>O<sub>3</sub> ceramic coating materials are extensively utilized on the inner chamber wall.
- First, the initial etching rate in the process chamber decreased.
- Second, the etching rate in the process chamber gradually increased.

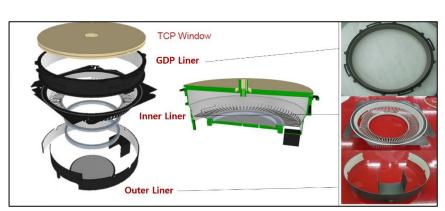


Fig. 1. Liner Parts(Inner Chamber Wall)



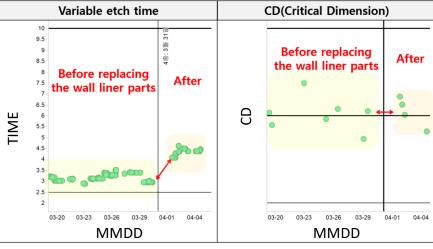
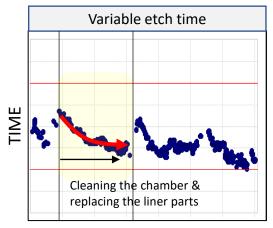


Fig. 2. Shift of the variable time to control with the same CD at a low etching rate after replacing wall liner parts.



MMDD

Fig. 3. Variable time depending on the date after replacing wall liner parts.

# Analyze: Fluorination of Y<sub>2</sub>O<sub>3</sub> coating material

- XPS analysis was performed at the end of the lifetime of the Upper and Inner liner.
- The F component was presented in the Y<sub>2</sub>O<sub>3</sub> coating
- It's Fluorination reaction.

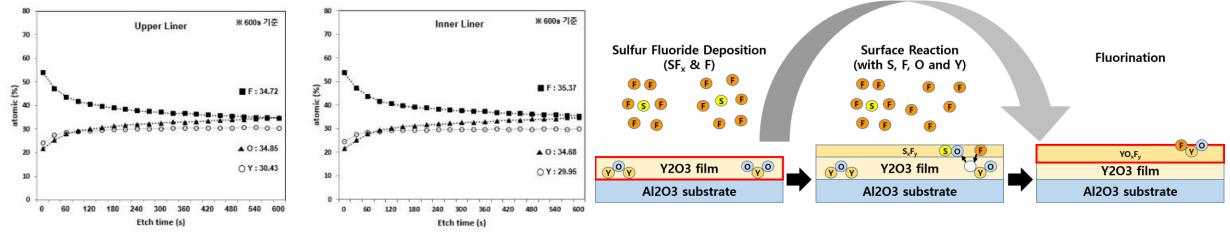


Fig. 4. Variations of chemical compositions measured using XPS with the sputtering time of the Upper Liner and Inner Liner parts after exposing to the fluorine plasma.

Fig. 5. Fluorination reaction of  $Y_2O_3$  film after exposing fluorine plasma.



# Solution: Pre-Treatment

expected outcomes and Pre-Treatment conditions

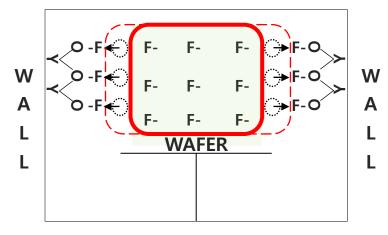


Fig. 6. Process chamber before pretreatment

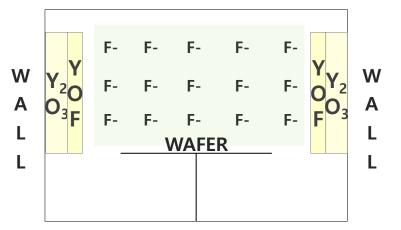


Fig. 7. Process chamber after pretreatment

Parameters	Non-treatment	Pre-treatment	_
RF power(W)	-	1000	
RF power, bias(W)	-	100	
Pressure(mTorr)	-	80	Table 1. Plasma etching
SF <sub>6</sub> (sccm)	-	200	parameters applied in this experiment to investigate the
Etching time(min)	-	720	influence of $SF_6$ plasma pre- treatment.



# Result : Improvement effect

- The initial etching rate of the process chamber decreased less by Pre-Treatment.
- The etching rate of the process chamber *increased slightly*.

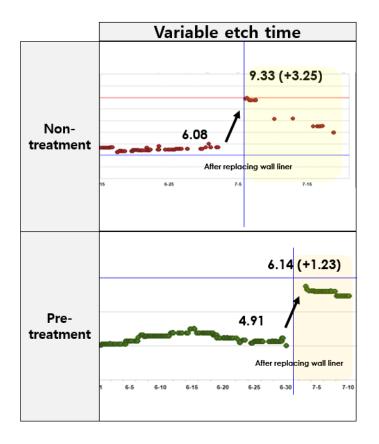




Fig. 8. Variable etch time trend of non-treatment and pre-treatment in etch process.

After replacing the wall liner parts	Time Drift
Non-treatment	+3.25
Pre-treatment	+1.23

Fig. 9. The difference in time drift between non-treatment and pre-treatment After replacing the wall liner parts.

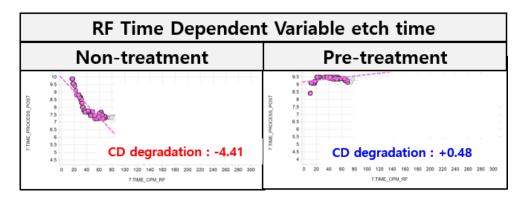


Fig. 10. Variable etch time slope according to RF time(<65hr) before and after SF<sub>6</sub> plasma pre-treatment in etch process.

## **Conclusion & Future**

#### Conclusion

-. Because of the **fluorination reaction** of Y2O3, the initial process condition of the chamber is **unstable**.

-. When <u>pre-treatment</u> is performed, the initial process condition is <u>relatively</u> <u>stable</u>.

- Future coating material
- -. Pre-treated Y2O3 coating requires up to 12 hours and is unproductive.

-. Since <u>YOF coating</u> does not require pre-treatment, it can be an <u>alternative</u> to pre-treated Y2O3 coating.

Types of liner parts coating	Pre-treatment duration	
Y <sub>2</sub> O <sub>3</sub>	12h	
YOF	Oh	

Table 2. Required Pre-treatment Time by Type ofcoating for liner Parts.

